

Chapter 1

Computer Abstractions and Technology

The Computer Revolution

- Progress in computer technology
 - Underpinned by Moore's Law
- Makes novel applications feasible
 - Computers in automobiles
 - Cell phones
 - Human genome project
 - World Wide Web
 - Search Engines
- Computers are pervasive

Classes of Computers

→ personal computer
→ server computer
→ super computers
→ embedded computer

■ Personal computers

- General purpose, variety of software
- Subject to cost/performance tradeoff

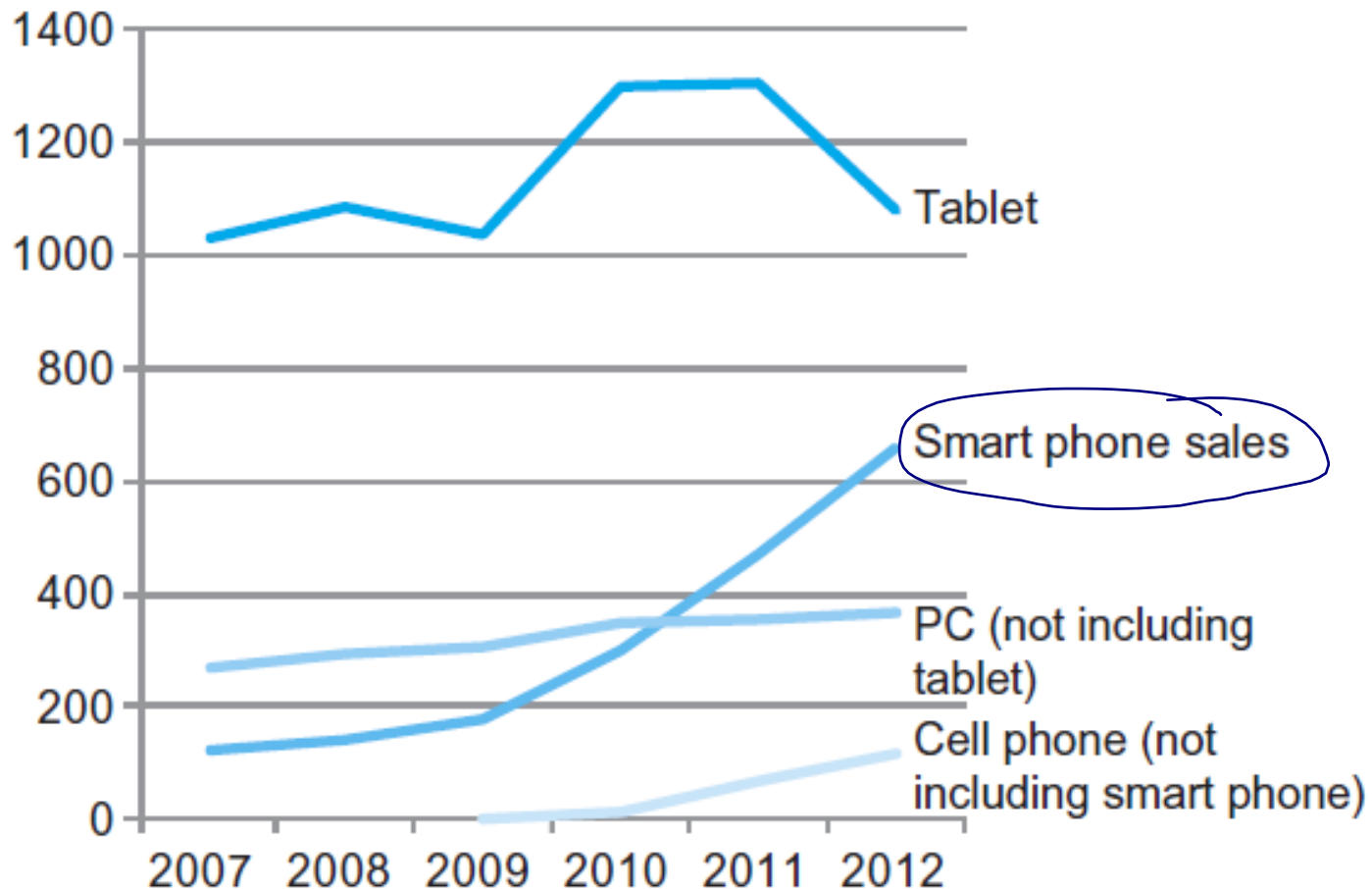
■ Server computers

- Network based
- High capacity, performance, reliability
- Range from small servers to building sized

Classes of Computers

- Supercomputers
 - High-end scientific and engineering calculations
 - Highest capability but represent a small fraction of the overall computer market
- Embedded computers
 - Hidden as components of systems
 - Stringent power/performance/cost constraints

The PostPC Era



The PostPC Era

- Personal Mobile Device (PMD)
 - Battery operated
 - Connects to the Internet
 - Hundreds of dollars
 - Smart phones, tablets, electronic glasses
- Cloud computing
 - Warehouse Scale Computers (WSC)
 - Software as a Service (SaaS)
 - Portion of software run on a PMD and a portion run in the Cloud
 - Amazon and Google

What You Will Learn

- How programs are translated into the machine language
 - And how the hardware executes them
- The hardware/software interface
- What determines program performance
 - And how it can be improved
- How hardware designers improve performance
- What is parallel processing

Understanding Performance

Algorithm

- Determines number of operations executed

Programming language, compiler, architecture

- Determine number of machine instructions executed per operation

Processor and memory system

- Determine how fast instructions are executed

I/O system (including OS)

- Determines how fast I/O operations are executed

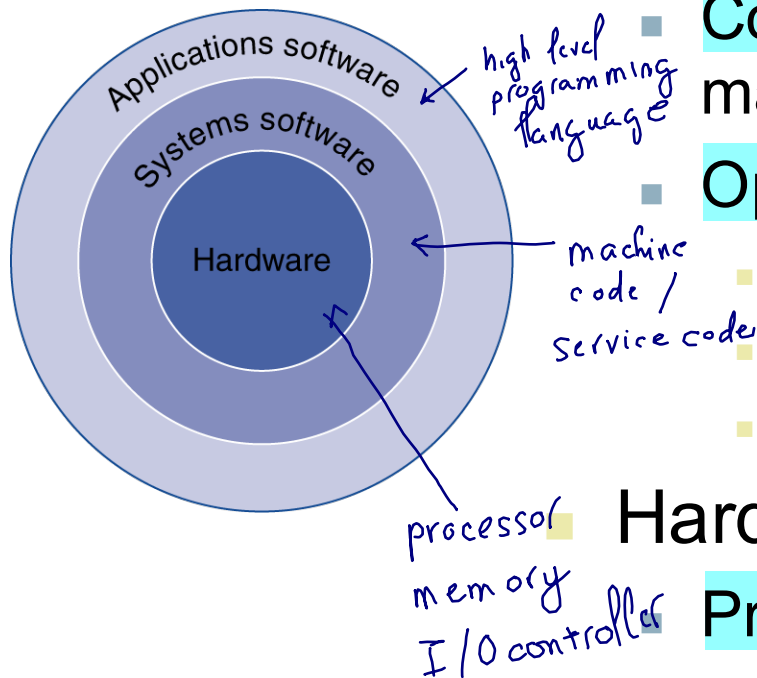
Eight Great Ideas

- Design for *Moore's Law*
- Use *abstraction* to simplify design
- Make the *common case fast*
- Performance via *parallelism*
- Performance via *pipelining*
- Performance via *prediction*
- *Hierarchy* of memories
- *Dependability* via redundancy



Below Your Program

- Application software
 - Written in high-level language
- System software



- **Compiler:** translates HLL code to machine code

- **Operating System:** service code

- Handling input/output
- Managing memory and storage
- Scheduling tasks & sharing resources

- **Hardware**

- **Processor, memory, I/O controllers**

Levels of Program Code

- **High-level language**
 - Level of abstraction closer to problem domain
 - Provides for productivity and portability
- **Assembly language**
 - Textual representation of instructions
- **Hardware representation**
 - Binary digits (bits)
 - Encoded instructions and data

High-level
language
program
(in C)

```
swap(int v[], int k)
{int temp;
  temp = v[k];
  v[k] = v[k+1];
  v[k+1] = temp;
}
```

Compiler

Assembly
language
program
(for MIPS)

```
swap:
  muli $2, $5, 4
  add  $2, $4, $2
  lw   $15, 0($2)
  lw   $16, 4($2)
  sw   $16, 0($2)
  sw   $15, 4($2)
  jr   $31
```

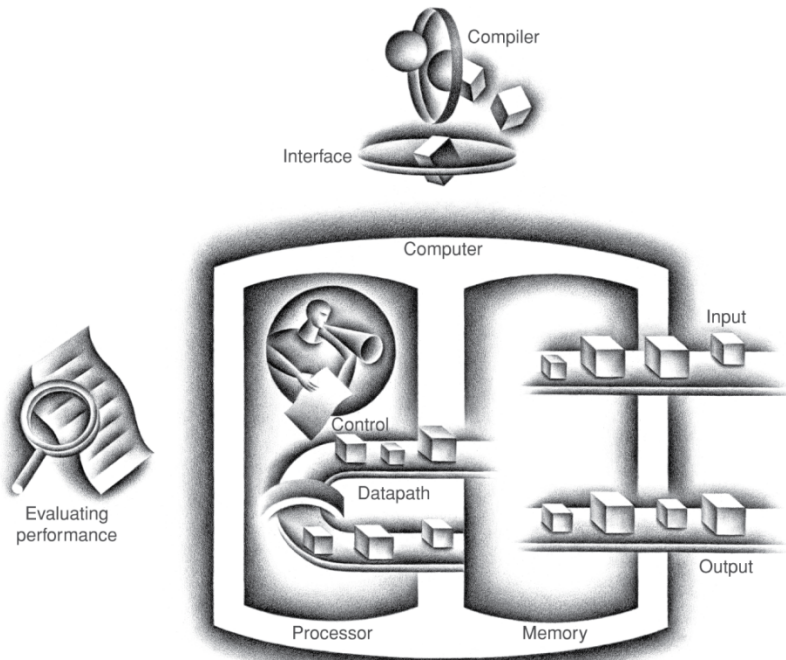
Assembler

Binary machine
language
program
(for MIPS)

```
000000001010000100000000000011000
000000000000110000001100000100001
100011000110001000000000000000000
100011001111001000000000000000100
101011001111001000000000000000000
101011000110001000000000000000100
00000011111000000000000000001000
```

Components of a Computer

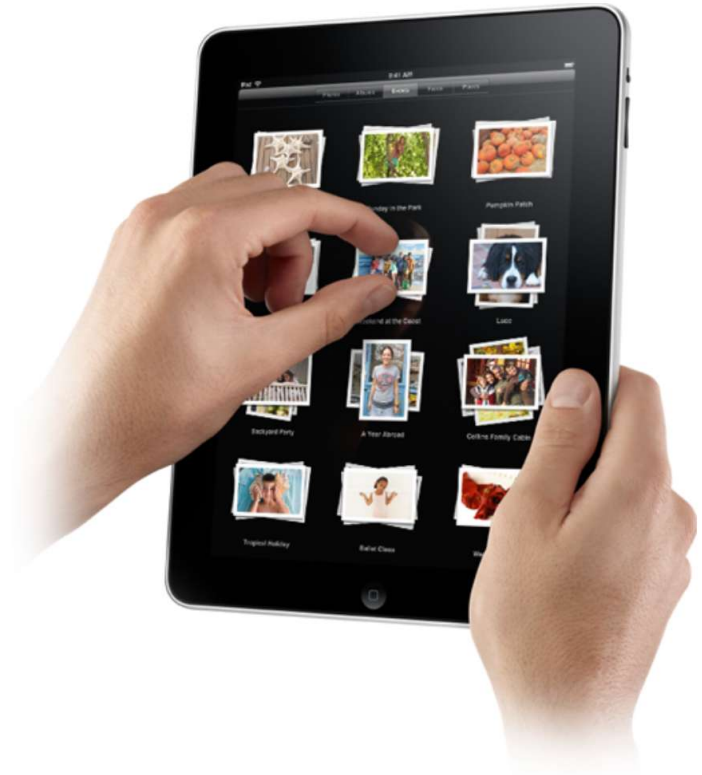
The BIG Picture



- Same components for all kinds of computer
 - Desktop, server, embedded
- Input/output includes
 - User-interface devices
 - Display, keyboard, mouse
 - Storage devices
 - Hard disk, CD/DVD, flash
 - Network adapters
 - For communicating with other computers

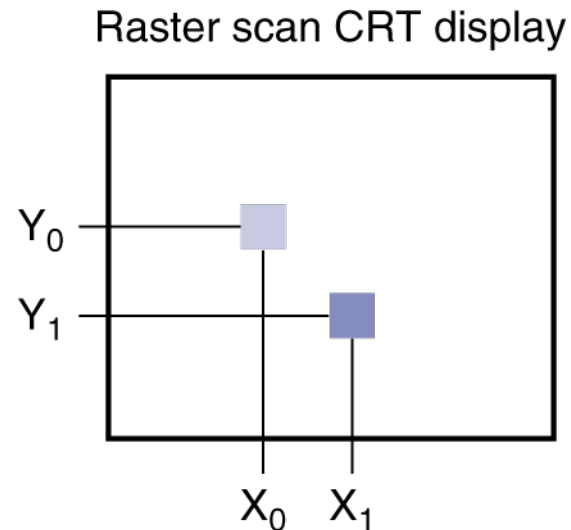
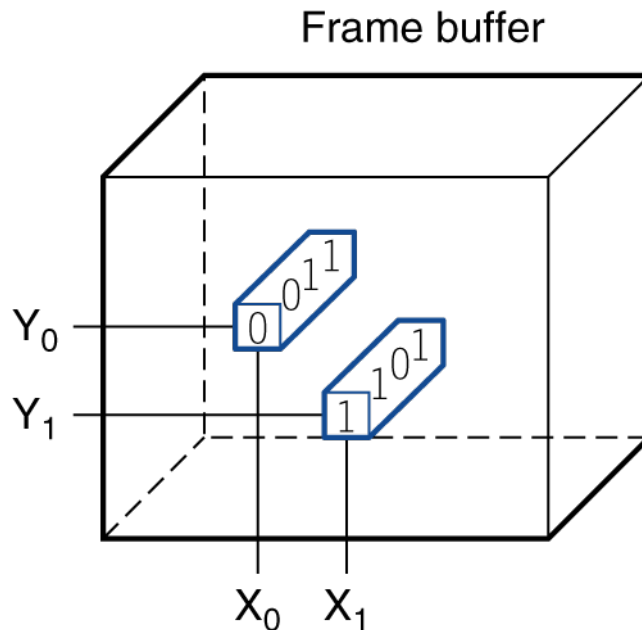
Touchscreen

- PostPC device
- Supersedes keyboard and mouse
- Resistive and Capacitive types
 - Most tablets, smart phones use capacitive
 - Capacitive allows multiple touches simultaneously

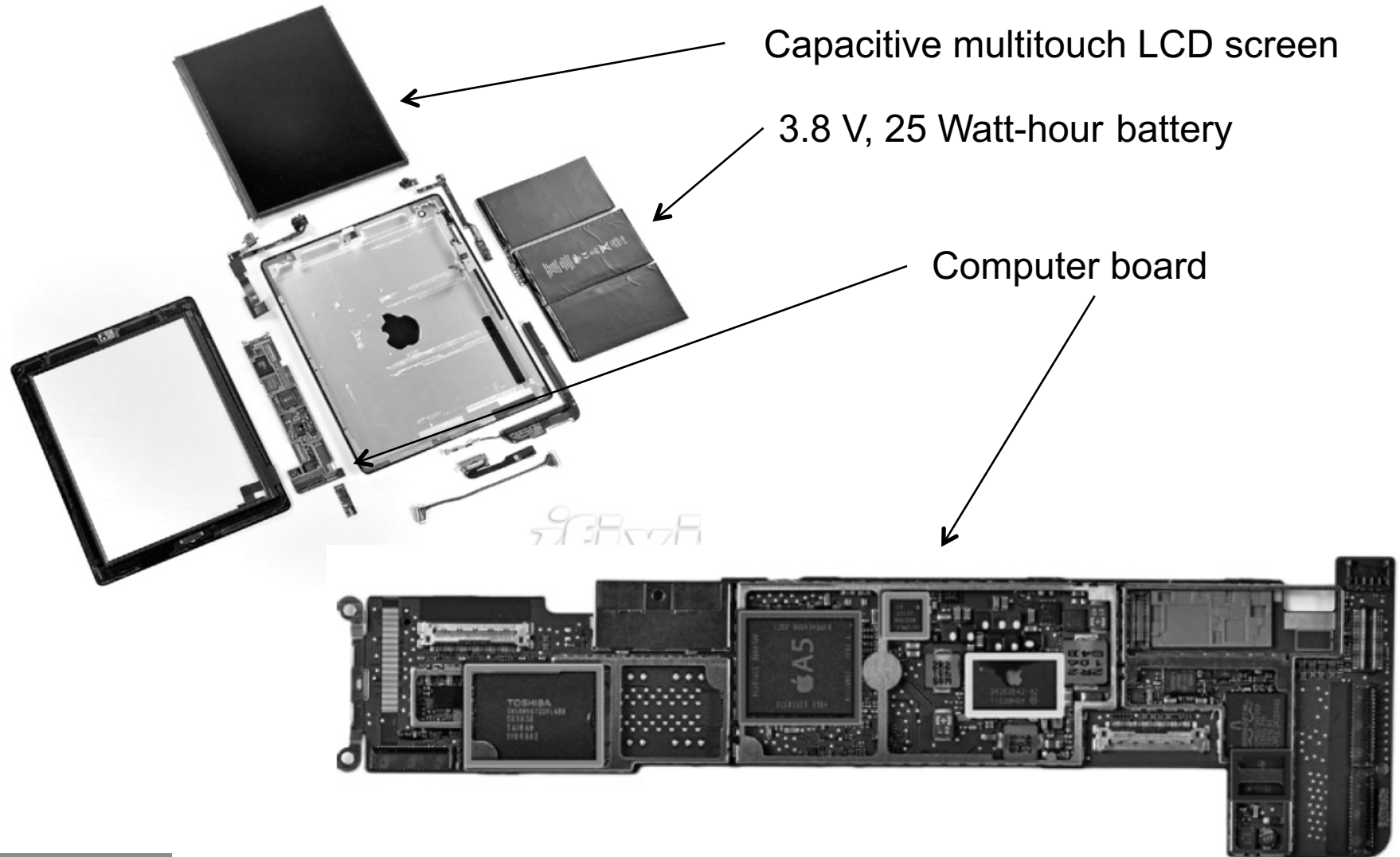


Through the Looking Glass

- LCD screen: picture elements (pixels)
 - Mirrors content of frame buffer memory



Opening the Box



Inside the Processor (CPU)

- Datapath: performs operations on data
- Control: sequences datapath, memory, ...
- Cache memory
 - Small fast SRAM memory for immediate access to data

Inside the Processor

- Apple A5



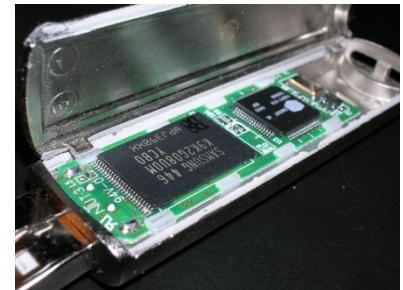
Abstractions

The BIG Picture

- Abstraction helps us deal with complexity
 - Hide lower-level detail
- Instruction set architecture (ISA)
 - The hardware/software interface
- Application binary interface
 - The ISA plus system software interface
- Implementation
 - The details underlying and interface

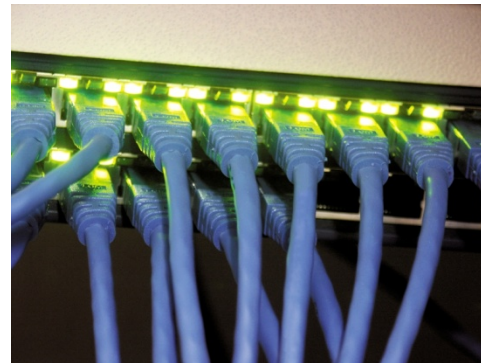
A Safe Place for Data

- Volatile main memory
 - Loses instructions and data when power off
- Non-volatile secondary memory
 - Magnetic disk
 - Flash memory
 - Optical disk (CDROM, DVD)



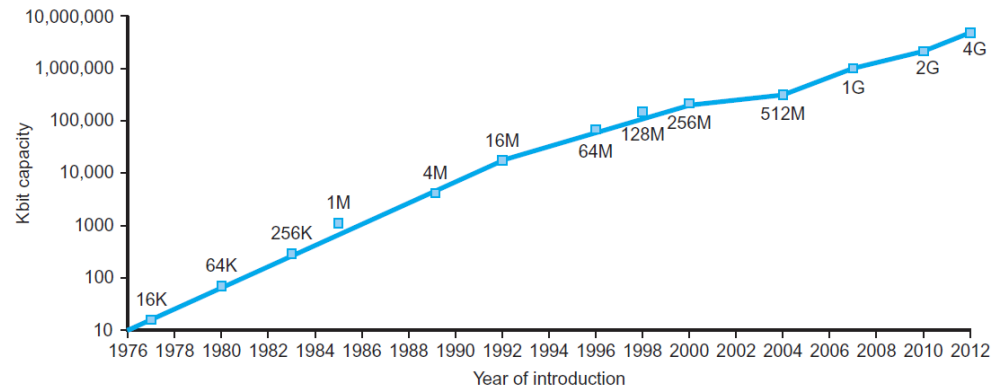
Networks

- Communication, resource sharing, nonlocal access
- Local area network (LAN): Ethernet
- Wide area network (WAN): the Internet
- Wireless network: WiFi, Bluetooth



Technology Trends

- Electronics technology continues to evolve
 - Increased capacity and performance
 - Reduced cost



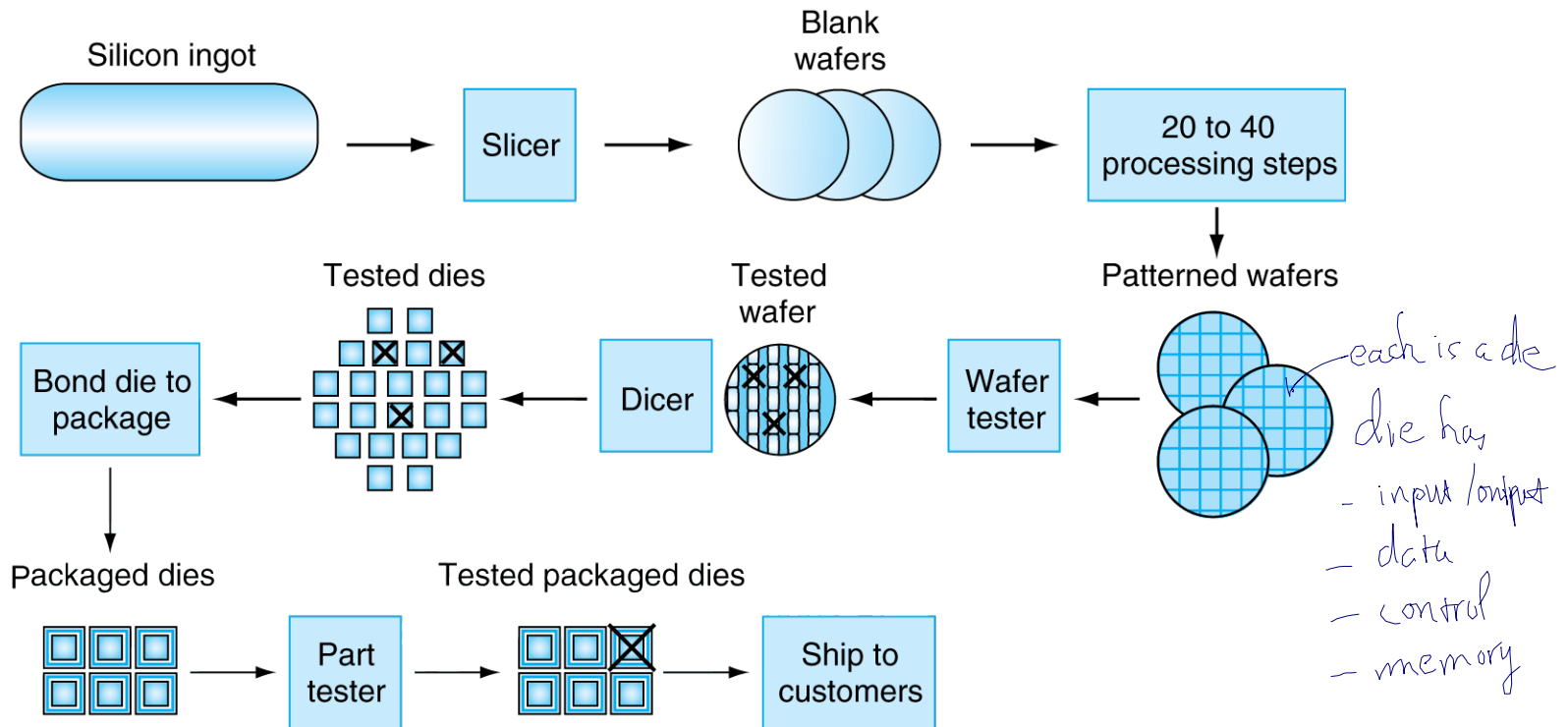
DRAM capacity

Year	Technology	Relative performance/cost
1951	Vacuum tube	1
1965	Transistor	35
1975	Integrated circuit (IC)	900
1995	Very large scale IC (VLSI)	2,400,000
2013	Ultra large scale IC	250,000,000,000

Semiconductor Technology

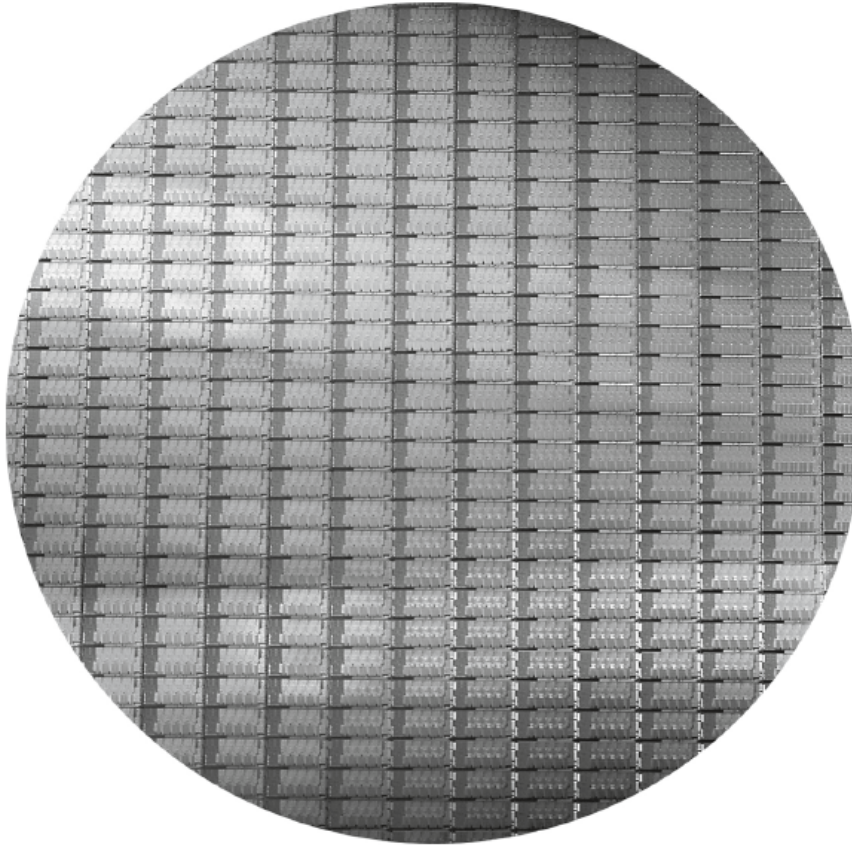
- Silicon: semiconductor
- Add materials to transform properties:
 - Conductors
 - Insulators
 - Switch

Manufacturing ICs



■ **Yield:** proportion of working dies per wafer

Intel Core i7 Wafer



- 300mm wafer, 280 chips, 32nm technology
- Each chip is 20.7 x 10.5 mm

Integrated Circuit Cost

$$\begin{aligned}\text{Cost per die} &= \frac{\text{Cost per wafer} \leftarrow \text{fixed.}}{\text{Dies per wafer} \times \text{Yield}} \\ \text{Dies per wafer} &\approx \text{Wafer area} / \text{Die area} \\ \text{Yield} &= \frac{1}{(1 + (\text{Defects per area} \times \text{Die area} / 2))^2}\end{aligned}$$

- Nonlinear relation to area and defect rate
 - Wafer cost and area are fixed
 - Defect rate determined by manufacturing process
 - Die area determined by architecture and circuit design